







(1.27 mm) .050"

SEAF-RA SERIES

HI-DENSITY RIGHT-ANGLE OPEN-PIN-FI

Up to **Board Mates:** 500 pins **SPECIFICATIONS** SEAM, SEAMF For complete specifications and recommended PCB layouts see www.samtec.com?SEAF-RA **Cable Mates:** Insulator Material: OTHER SOLUTIONS Contact Material: Copper Alloy GPSK-01-01

Current Rating: 1.9 A per pin (10 pins powered) Operating Temp Range: 55 °C to +125 °C -55 °C to +125 °C

Plating:
Au or Sn over
50 μ" (1.27 μm) Ni

Working Voltage:

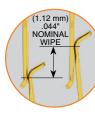
Mated Cycles: **RoHS Compliant:**

Lead-Free Solderable:

RECOGNITIONS

For complete scope of www.samtec.com/quality









Solder charge terminations Optional guide post

holes

HIGH-SPEED CHANNEL PERFORMANCE

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com



extraction forces

SOLDER







-20, -30.40. –50

NO. OF ROWS	Α	В	С
-04	(13.26) .522	(13.77) .542	(7.91) .311
-06	(15.80) .622	(16.31) .642	(10.45) .411
-08	(18.34) .722	(18.85) .742	(12.99) .511
-10	(20.88) .822	(21.39) .842	(15.53) .611

= 10 µ" (0.25 µm) Gold on contact area

Matte Tin on solder tail

= 30 µ" (0.76 µm) Gold on contact area Matte Tin on solder tail

-04= Four Rows

-06 = Six Rows

-08* = Eight Rows

-10*= Ten Rows

: Tin/Lead Alloy Solder Charge

= Lead-Free Solder Charge

*Note: Fixturing required to process eight and ten row options, see www.samtec.com/ searayfixture

-GP

= Guide = Standard Post Hole Tape & Reel

_LP = Latch Post -06 row -30 positions only) (Mates to

SEAC Series)

–K = Polyimide film Pick & Place Pad

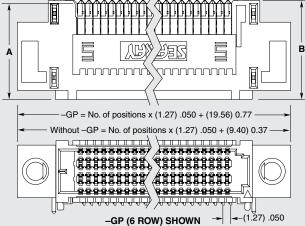
(27.25) 1.073

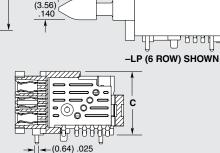
–FR = Full Reel Tape & Reel (must order maximum

quantity per reel; contact Samtec for quantity breaks)

ALSO AVAILABLE (MOQ Required)

· Other platings





Some sizes, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice **WWW.SAMTEC.COM**